



年程科技股份有限公司  
TECSTAR TECHNOLOGY CO., LTD.

# TB 321611 G601



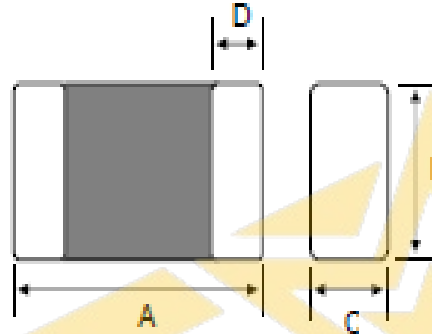
Physical Dimensions : mm (inch)

A =  $3.2 \pm 0.2$  (0.126 $\pm$ 0.008)

B =  $1.6 \pm 0.2$  (0.063 $\pm$ 0.008)

C =  $1.1 \pm 0.2$  (0.043 $\pm$ 0.008)

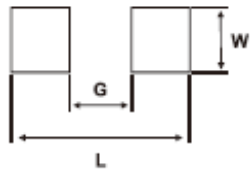
D =  $0.5 \pm 0.3$  (0.020 $\pm$ 0.012)



General Information :

1. Termination Finish is 100% Tin.
2. Components Should be Adequately Preheated Before Soldering.
3. Operating Temperature: -55°C to +125°C
4. Storage Temperature (on Tape & Reel): 40°C MAX. , 70% RH

Land Patterns for Reflow Soldering



| L           | W           | G           |
|-------------|-------------|-------------|
| 4.40(0.173) | 1.80(0.071) | 1.20(0.047) |

Packing Method:

One reel = 3,000 pcs

One Box = 150,000 pcs

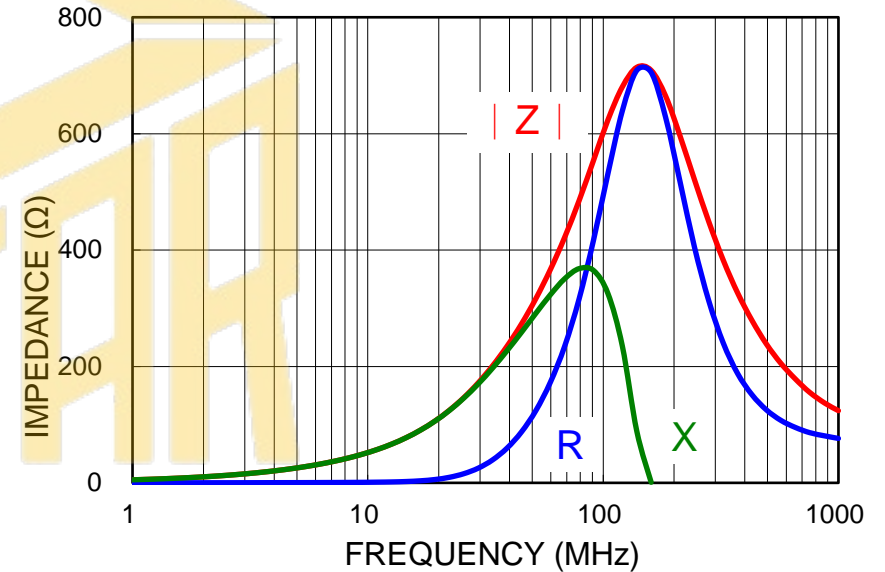
One Box = 9.3 KG

Electrical Characteristics :

|           | Value | Unit     | Tolerance  | Test Condition |
|-----------|-------|----------|------------|----------------|
| Impedance | 600   | $\Omega$ | $\pm 25\%$ | 100MHz / 100mV |
| DCR       | 0.30  | $\Omega$ | Max.       |                |
| IDC       | 200   | mA       | Max.       |                |

Typical Impedance Characteristics : HP 4291B

## TB321611G601



### Multilayer Ferrite Chip Beads

P/N

TB 321611 G601

Version

N000



+886-3-4962286

www.tecstar.com.tw

N000  
VER.

Initial  
DESCRIPTION

DATE

BY